1. Product profile

1.1 General description

Single planar Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a very small and flat lead SOD323F (SC-90) Surface-Mounted Device (SMD) plastic package.

1.2 Features and benefits

- Low forward voltage
- Reverse voltage $V_R \leq 100$ V
- Very small and flat lead SMD plastic package
- Low capacitance
- AEC-Q101 qualified

1.3 Applications

- High-speed switching
- Line termination
- Voltage clamping
- Reverse polarity protection

1.4 Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td></td>
<td>-</td>
<td>-</td>
<td>100</td>
<td>V</td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 250$ mA</td>
<td>$\uparrow$</td>
<td>-</td>
<td>-</td>
<td>mV</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 75$ V</td>
<td>$\uparrow$</td>
<td>-</td>
<td>-</td>
<td>$4 \ \mu$A</td>
</tr>
</tbody>
</table>

[1] Pulse test: $t_p \leq 300 \ \mu$s; $\delta \leq 0.02$.

2. Pinning information

<table>
<thead>
<tr>
<th>Pin</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>cathode</td>
<td>![simplified outline]</td>
<td>![graphic symbol]</td>
</tr>
<tr>
<td>2</td>
<td>anode</td>
<td>![simplified outline]</td>
<td>![graphic symbol]</td>
</tr>
</tbody>
</table>

[1] The marking bar indicates the cathode.
3. Ordering information

Table 3. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package Name</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>BAT46WJ</td>
<td>SC-90</td>
<td>plastic surface-mounted package; 2 leads</td>
<td>SOD323F</td>
</tr>
</tbody>
</table>

4. Marking

Table 4. Marking codes

<table>
<thead>
<tr>
<th>Type number</th>
<th>Marking code</th>
</tr>
</thead>
<tbody>
<tr>
<td>BAT46WJ</td>
<td>JK</td>
</tr>
</tbody>
</table>

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{R}$</td>
<td>reverse voltage</td>
<td>-</td>
<td>100</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>$I_{F}$</td>
<td>forward current</td>
<td>-</td>
<td>250</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>$I_{FSM}$</td>
<td>non-repetitive peak forward current</td>
<td>square wave; $t_p &lt; 10$ ms</td>
<td>2.5</td>
<td>A</td>
<td></td>
</tr>
<tr>
<td>$P_{tot}$</td>
<td>total power dissipation</td>
<td>$T_{amb} \leq 25$ °C</td>
<td>400</td>
<td>mW</td>
<td></td>
</tr>
<tr>
<td>$T_j$</td>
<td>junction temperature</td>
<td>-</td>
<td>150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>$T_{amb}$</td>
<td>ambient temperature</td>
<td>-55</td>
<td>+150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>$T_{stg}$</td>
<td>storage temperature</td>
<td>-65</td>
<td>+150</td>
<td>°C</td>
<td></td>
</tr>
</tbody>
</table>

[4] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 6. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$R_{(th)}$</td>
<td>thermal resistance from junction to ambient</td>
<td>in free air</td>
<td>310</td>
<td>K/W</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

[13] $R_{(th)}$ is a function of the thermal resistance from the case to the ambient.
Table 6. Thermal characteristics …continued

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$R_{th(j-sp)}$</td>
<td>thermal resistance from junction to solder point</td>
<td>[4]</td>
<td>-</td>
<td>-</td>
<td>35</td>
<td>kW</td>
</tr>
</tbody>
</table>

[3] Reflow soldering is the only recommended soldering method.

---

**Fig 1.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

**Fig 2.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
7. Characteristics

Table 7. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 0.1$ mA</td>
<td>-</td>
<td>175</td>
<td>200</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 10$ mA</td>
<td>-</td>
<td>315</td>
<td>350</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 10$ mA; $T_j = -40$ °C</td>
<td>-</td>
<td>-</td>
<td>470</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 50$ mA</td>
<td>-</td>
<td>415</td>
<td>475</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 50$ mA; $T_j = -40$ °C</td>
<td>-</td>
<td>-</td>
<td>560</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 250$ mA</td>
<td>-</td>
<td>710</td>
<td>850</td>
<td>mV</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 1.5$ V</td>
<td>-</td>
<td>0.2</td>
<td>0.5</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 1.5$ V; $T_j = 60$ °C</td>
<td>-</td>
<td>-</td>
<td>12</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 10$ V</td>
<td>-</td>
<td>0.3</td>
<td>0.8</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 10$ V; $T_j = 60$ °C</td>
<td>-</td>
<td>-</td>
<td>20</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 50$ V</td>
<td>-</td>
<td>0.7</td>
<td>2</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 50$ V; $T_j = 60$ °C</td>
<td>-</td>
<td>-</td>
<td>44</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 75$ V</td>
<td>-</td>
<td>1</td>
<td>4</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 75$ V; $T_j = 60$ °C</td>
<td>-</td>
<td>-</td>
<td>80</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 100$ V</td>
<td>-</td>
<td>2</td>
<td>9</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 100$ V; $T_j = 60$ °C</td>
<td>-</td>
<td>-</td>
<td>120</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 100$ V; $T_j = 85$ °C</td>
<td>-</td>
<td>-</td>
<td>600</td>
<td>μA</td>
</tr>
<tr>
<td>$C_d$</td>
<td>diode capacitance</td>
<td>$f = 1$ MHz</td>
<td>$V_R = 0$ V</td>
<td>-</td>
<td>39</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 1$ V</td>
<td>-</td>
<td>-</td>
<td>21</td>
<td>pF</td>
</tr>
<tr>
<td>$t_{rr}$</td>
<td>reverse recovery time</td>
<td>$t_p \leq 300$ μs; $\delta \leq 0.02$</td>
<td>$I_R = 10$ mA</td>
<td>$R_L = 100$ Ω</td>
<td>measured at $I_R = 1$ mA</td>
<td></td>
</tr>
</tbody>
</table>

[1] Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.

[2] When switched from $I_F = 10$ mA to $I_R = 10$ mA; $R_L = 100$ Ω; measured at $I_R = 1$ mA.
Fig 3. Forward current as a function of forward voltage; typical values

(1) $T_{amb} = 150 \, ^\circ C$
(2) $T_{amb} = 125 \, ^\circ C$
(3) $T_{amb} = 80 \, ^\circ C$
(4) $T_{amb} = 25 \, ^\circ C$
(5) $T_{amb} = -40 \, ^\circ C$

Fig 4. Reverse current as a function of reverse voltage; typical values

(1) $T_{amb} = 125 \, ^\circ C$
(2) $T_{amb} = 80 \, ^\circ C$
(3) $T_{amb} = 60 \, ^\circ C$
(4) $T_{amb} = 25 \, ^\circ C$
(5) $T_{amb} = -40 \, ^\circ C$

Fig 5. Diode capacitance as a function of reverse voltage; typical values

$f = 1 \, MHz; T_{amb} = 25 \, ^\circ C$
Single Schottky barrier diode

$T_j = 125 \, ^\circ C$

1. $\delta = 1$
2. $\delta = 0.9$
3. $\delta = 0.8$
4. $\delta = 0.5$

**Fig 6.** Average reverse power dissipation as a function of reverse voltage; typical values

$T_j = 150 \, ^\circ C$

1. $\delta = 1; DC$
2. $\delta = 0.5; f = 20 \, kHz$
3. $\delta = 0.2; f = 20 \, kHz$
4. $\delta = 0.1; f = 20 \, kHz$

**Fig 7.** Average forward current as a function of ambient temperature; typical values

FR4 PCB, mounting pad for cathode 1 cm$^2$

$T_j = 150 \, ^\circ C$

1. $\delta = 1; DC$
2. $\delta = 0.5; f = 20 \, kHz$
3. $\delta = 0.2; f = 20 \, kHz$
4. $\delta = 0.1; f = 20 \, kHz$

**Fig 8.** Average forward current as a function of ambient temperature; typical values

$T_j = 150 \, ^\circ C$

1. $\delta = 1; DC$
2. $\delta = 0.5; f = 20 \, kHz$
3. $\delta = 0.2; f = 20 \, kHz$
4. $\delta = 0.1; f = 20 \, kHz$

**Fig 9.** Average forward current as a function of solder point temperature; typical values
8. Test information

The current ratings for the typical waveforms as shown in Figure 7, 8 and 9 are calculated according to the equations: $I_{F(A,V)} = I_M \times \delta$ with $I_M$ defined as peak current, $I_{\text{RMS}} = I_{F(A,V)} \text{ at DC}$, and $I_{\text{RMS}} = I_M \times \sqrt{\delta}$ with $I_{\text{RMS}}$ defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

Fig 10. Reverse recovery time test circuit and waveforms

Fig 11. Duty cycle definition
9. Package outline

![Diagram of package outline SOD323F (SC-90)]

Fig 12. Package outline SOD323F (SC-90)

10. Packing information

Table 8. Packing methods

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Description</th>
<th>Packing quantity</th>
</tr>
</thead>
<tbody>
<tr>
<td>BAT46WJ</td>
<td>SOD323F</td>
<td>4 mm pitch, 8 mm tape and reel</td>
<td>3000</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>-115</td>
</tr>
</tbody>
</table>

[1] For further information and the availability of packing methods, see Section 14.

11. Soldering

![Diagram of reflow soldering footprint SOD323F (SC-90)]

Reflow soldering is the only recommended soldering method.

Fig 13. Reflow soldering footprint SOD323F (SC-90)
12. Revision history

Table 9. Revision history

<table>
<thead>
<tr>
<th>Document ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
</tr>
</thead>
<tbody>
<tr>
<td>BAT46WJ v.2</td>
<td>20111108</td>
<td>Product data sheet</td>
<td>-</td>
<td>BAT46WJ v.1</td>
</tr>
<tr>
<td>BAT46WJ v.1</td>
<td>20100728</td>
<td>Product data sheet</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>

Modifications:
- Table 7: unit for reverse current $I_R$ at $V_R = 50$ V corrected to $\mu$A
- Table 7: conditions of reverse voltage $V_R$ corrected
- Section 13 “Legal information”: updated
13. Legal information

13.1 Data sheet status

<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
<td></td>
</tr>
<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
</tr>
<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
</tr>
</tbody>
</table>

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term ‘short data sheet’ is explained in section “Definitions”.
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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For sales office addresses, please send an email to: salesaddresses@nxp.com
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